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|--------------------------|--|-------------------------------------|---------------------|
| PCN Number: | 20150304000 | PCN Date: | 03/09/2015 |
| Title: | Datasheet update for MSP430F5132/52/72 | | |
| Customer Contact: | PCN Manager | Dept: | Quality Services |
| Change Type: | | | |
| <input type="checkbox"/> | Assembly Site | <input type="checkbox"/> | Design |
| <input type="checkbox"/> | Assembly Process | <input checked="" type="checkbox"/> | Data Sheet |
| <input type="checkbox"/> | Assembly Materials | <input type="checkbox"/> | Part number change |
| <input type="checkbox"/> | Mechanical Specification | <input type="checkbox"/> | Test Site |
| <input type="checkbox"/> | Packing/Shipping/Labeling | <input type="checkbox"/> | Test Process |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Site |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Material |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Bump Process |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Site |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Materials |
| <input type="checkbox"/> | | <input type="checkbox"/> | Wafer Fab Process |

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing an information-only product change notification.

The product datasheet(s) is being updated as summarized below.

The following change history provides further details:



www.ti.com

**MSP430F5172, MSP430F5152, MSP430F5132
MSP430F5171, MSP430F5151, MSP430F5131**

SLAS619N – AUGUST 2010 – REVISED JANUARY 2015

Changes from Revision M (May 2014) to Revision N

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| | |
|--|--------------------|
| • Moved T_{stg} to Section 5.1 | 12 |
| • Added Section 5.2, ESD Ratings | 12 |
| • Added notes (1) through (3) to Section 5.35, USCI (SPI Master Mode) | 32 |
| • Added notes (1) through (3) to Section 5.36, USCI (SPI Slave Mode) | 34 |
| • Changed the MAX limit of E_G "Gain error, external reference, buffered" from ± 1.5 LSB to ± 5 LSB in Section 5.40 .. | 38 |
| • Removed specification for E_T "Total unadjusted error, external buffered and unbuffered reference" in Section 5.40 . | 38 |
| • Moved <i>Input/Output Schematics</i> to Section 6.10 | 71 |
| • Moved <i>Device Descriptors</i> to Section 6.11 | 88 |

The datasheet number will be changing.

| | | |
|-----------------------------------|--------------|-----------------|
| Device Family | Change From: | Change To: |
| MSP430F5132/52/72 | SLAS619M | SLAS619N |

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/msp430f5172>

Reason for Change:

To more accurately reflect device characteristics.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

Electrical specification performance changes as indicated above.

Changes to product identification resulting from this PCN:

None.

| Product Affected: | | | |
|--------------------------|------------------|------------------|------------------|
| MSP430F5132IDA | MSP430F5132IYFFT | MSP430F5152IYFFR | MSP430F5172IRSBT |
| MSP430F5132IDAR | MSP430F5152IDA | MSP430F5152IYFFT | MSP430F5172IYFFR |
| MSP430F5132IRSBR | MSP430F5152IDAR | MSP430F5172IDA | MSP430F5172IYFFT |
| MSP430F5132IRSBT | MSP430F5152IRSBR | MSP430F5172IDAR | |
| MSP430F5132IYFFR | MSP430F5152IRSBT | MSP430F5172IRSBR | |

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

| Location | E-Mail |
|-----------------|--|
| USA | PCNAmericasContact@list.ti.com |
| Europe | PCNEuropeContact@list.ti.com |
| Asia Pacific | PCNAsiaContact@list.ti.com |
| Japan | PCNJapanContact@list.ti.com |